

NOTES:

1. Unless otherwise specified:
  - non dimensioned radii max R0.2mm
  - non dimensioned edges rounded with R0.3mm
2. Plating thickness:
  - Sn 100% 5~10um
  - Ni 1.27~2.0um

REV.	REVISIONS	REC.	DATE	REV.	REVISIONS	REC.	DATE

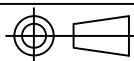
DRAWN & DRAFTED BY	QINMENG	TOLERANCES		ANGLE:	TITLE:		
		0<L≤4 ±0.1	pin pitch ±0.2	±1°	SMD BOBBIN EP-5		
CHECKED & APPROVED BY		4<L≤16 ±0.2		UNIT:	BOBBIN MATERIAL:	UL REC.	
		16<L≤63 ±0.3	MM	PM 9630 JT	UL 94V-0		
			ORIGIN:	PIN MATERIAL:	PIN TENSION LOAD:		
			DG	C5191 H	1.0KG/MIN		
				DATE:	DRAWING NO.	REV.	
				AUG.24.2018	S-511-1	0	



PIN SHINE INDUSTRIAL CO., LTD.

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DATE: AUG.24.2018

DRAWING NO.

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REV. 0